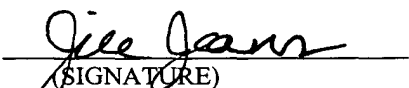


14230 U.S. PTO  
07/31/03

PATENT APPLICATION  
Docket No. 8750-045  
Client No. SPX2003060020US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

EXPRESS MAIL	MAILING LABEL NO. <u>EL982121150US</u> DATE OF DEPOSIT: <u>JULY 31, 2003</u>
I HEREBY CERTIFY THAT THIS PAPER AND ENCLOSURES AND/OR FEE ARE BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE "EXPRESS MAIL POST OFFICE TO ADDRESSEE" SERVICE UNDER 37 CFR 1.10 ON THE DATE INDICATED ABOVE AND IS ADDRESSED TO: MAIL STOP PATENT APPLICATION, COMMISSIONER FOR PATENTS, P.O. BOX 1450, ALEXANDRIA, VA 22313-1450.	
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22151 U.S. PTO  
10/632700  
07/31/03

Mail Stop Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Enclosed for filing is a patent application under 37 CFR 1.53(b) of:

Inventor: In-Ku Kang, Hee-Kook Choi, Sang-Ho An and Sang-Yeop Lee

For: MULTI-CHIP MODULE HAVING BONDING WIRES AND METHOD  
OF FABRICATING THE SAME

Applicant requests FIG. 3 to be published with the application.

Enclosures:

- ☒ Specification (pages 1-7; claims (pages 8-11); abstract (page 12)
- ☒ THREE sheet(s) of FORMAL drawings (comprising 6 figures)
- ☒ PTO form 1449 Information Disclosure Statement with 4 cited references
- ☒ Return Postcard

CLAIMS AS FILED				
For	Number Filed	Number Extra	Rate	Basic Fee \$750
Total Claims	25-20	5	x \$ 18 =	\$90.00
Independent Claims	3-3	0	x \$ 84 =	\$0.00
TOTAL FILING FEE				\$840.00

☒ Combined Declaration and Power of Attorney (unsigned)

☒ Newly executed (original or copy)

☐ Assignment with cover sheet

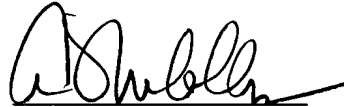
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Respectfully submitted,

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